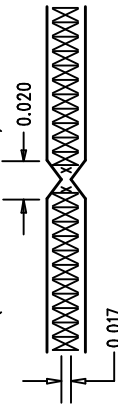


LAYERING STRUCTURE

NOTES : Unless Otherwise Specified

1. FAB PER IPC-A-600. PCBs ARE TO BE ROHS COMPLIANT.
2. MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4.
- 2 OZ. COPPER FINISH ON OUTER LAYERS.
- 1 OZ. COPPER FINISH ON INNER LAYERS.
- THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
- FLAMABILITY RATING: 94 V-0 MINIMUM .
- 0.00 ARE PRIMARY DATUMS.
4. DRILLING: DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, .001 INCH THICK MIN. ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
- HOLE LOCATION TOLERANCES ARE +/- .003 INCH IN RELATION TO CENTER
5. FINISH: SMOBC USING LPI BOTH SIDES COLOR **BLACK**
- GOLD IMMERSION BOTH SIDES.
6. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
7. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE BUT YOU MAY MODIFY PAD SIZE TO MEET END FINISH.
8. FINGER AREA; GOLD PLATE TO MIN. OF .00003 IN. PER MIL-G-45204, TYP II, CL1, GRADE C, OVER .0002 IN. LOW STRESS NICKEL PER QQ-N-290, CL2.
9. OUTER DIELECTRIC THICKNESS: TARGET 50-0HM USING 25 MIL TRACE CONTROLLED 50 OHM IMPEDANCE FROM LAYER 1 TO LAYER 2 AND LAYER 4 TO LAYER 3 (TO BE FINALIZED BY MANUFACTURER)
10. SCORING: (FOR PRODUCTION RUN)



SIZE	QTY	SYM	PLATED	TOL
10	903	+	YES	+/-0.0
70	2	X	NO	+/-0.0
187	4	□	YES	+/-0.0
35	12	◇	YES	+/-0.0
65	5	⊠	YES	+/-0.0
95	2	⊠	YES	+/-0.0

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON ANGLE ± 1
2 PLACE $\pm .01$ 3 PLACE $\pm .005$
INTERPRET DIM AND TOL
PER ASME Y14.5M - 1994

APPROVALS

	INIT	DATE
DRAWN		
CHECK		
DESIGN	J. Wu	5/7/07
ENGR	C. Pei	5/7/07
SCALE = NONE		

LINEAR
TECHNOLOGY

TITLE: LTC6416CDDDB
16-Bit ADC Buffer + ADC

SIZE A	DEMO	DC1257B	REV. B
			SHT 1 of 1

SHT 1 of 1